

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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# **Three Line EMI Filter**

This device is a three-line EMI filter array for SIM Card wireless applications. Greater than -25 dB attenuation is obtained at frequencies from 800 MHz to 2.2 GHz. ESD protection is provided across all capacitors.

#### **Features**

- EMI Filtering and ESD Protection
- Integration of 10 Discretes
- Provides Protection for IEC61000-4-2 (Level 4)
  - ♦ 8.0 kV (Contact)
  - ◆ 15 kV (Air)
- Flip-Chip Package
- Moisture Sensitivity Level 1
- ESD Rating: Machine Model = C; Human Body Model = 3B
- Pb-Free Package is Available\*

#### **Benefits**

- Reduces EMI/RFI Emissions on a Data Line
- Integrated Solution Offers Cost and Space Savings
- Reduces Parasitic Inductances Which Offer a More "Ideal" Low Pass Filter Response
- Integrated Solution Improves System Reliability

# **Applications**

- SIM Card
- EMI Filtering and ESD Protection for Data Lines
- Cell Phones
- Handheld Products

# MAXIMUM RATINGS (T<sub>A</sub> = 25°C unless otherwise noted)

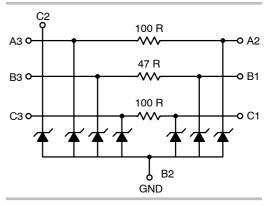
Rating		Symbol	Value	Unit
ESD Discharge IEC61000-4-2	Air Discharge	V <sub>PP</sub>	15	kV
IEC01000-4-2	Contact Discharge		8.0	
Steady-State Power per Resistor		$P_{R}$	100	mW
Steady-State Power per Package		PT	300	mW
Operating Temperature Range		T <sub>OP</sub>	-40 to +85	°C
Storage Temperature Range		T <sub>STG</sub>	-55 to +150	°C
Junction Temperature		TJ	+125	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



# ON Semiconductor®

## http://onsemi.com





# 8-Pin Flip-Chip FC SUFFIX CASE 499AG





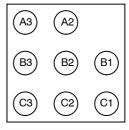
3101 = Specific Device Code A = Assembly Location

Y = Year WW = Work Week

■ = Pb-Free Package

(Note: Microdot may be in either location)

# PIN CONFIGURATION



## **ORDERING INFORMATION**

Device	Package	Shipping†
NUF3101FCT1	Flip-Chip	3000 Tape & Reel
NUF3101FCT1G	Flip-Chip (Pb-Free)	3000 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Test Conditions	Min	Тур	Max	Unit
Maximum Reverse Working Voltage	V <sub>RWM</sub>	-	-	_	5.6	V
Breakdown Voltage	$V_{BR}$	I <sub>R</sub> = 1.0 mA	6.0	_	8.0	V
Leakage Current	I <sub>R</sub>	V <sub>RM</sub> = 3.0 V	-	_	0.1	μΑ
Series Resistance	R <sub>1</sub>	-	80	100	120	Ω
Series Resistance	R <sub>2</sub>	=	38	47	56	Ω
Series Resistance	R <sub>3</sub>	-	80	100	120	Ω
Capacitance	C <sub>LINE 1</sub>	f = 1.0 MHz, 0 Vdc	-	_	40	pF
Cut-Off Frequency	f <sub>3dB</sub>	50 $\Omega$ Source and 50 $\Omega$ Load Termination	100	_	300	MHz

# **TYPICAL PERFORMANCE CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise specified})$ 

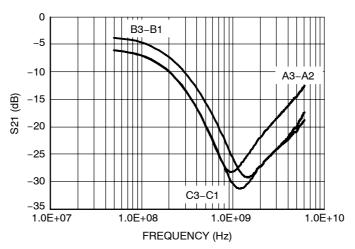


Figure 1. Insertion Loss Characteristics

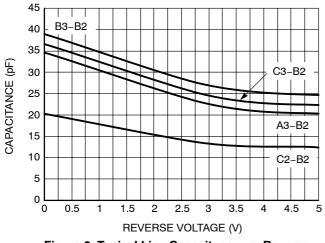


Figure 2. Typical Line Capacitance vs. Reverse Bias Voltage

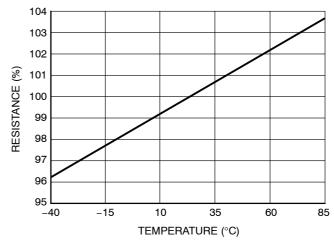


Figure 3. Typical Normalized Resistance Over Temperature

# PRINTED CIRCUIT BOARD RECOMMENDATIONS

Parameter	500 μm Pitch 300 or 350 μm Solder Ball
PCB Pad Size	250 μm +25 –0
Pad Shape	Round
Pad Type	NSMD
Solder Mask Opening	350 μm ±25
Solder Stencil Thickness	125 μm
Stencil Aperture	250 x 250 μm sq.
Solder Flux Ratio	50/50
Solder Paste Type	No Clean Type 3 or Finer
Trace Finish	OSP Cu
Trace Width	150 μm Max

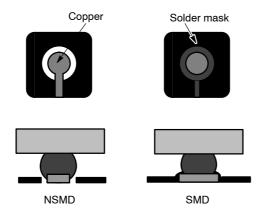


Figure 4. NSMD vs. SMD

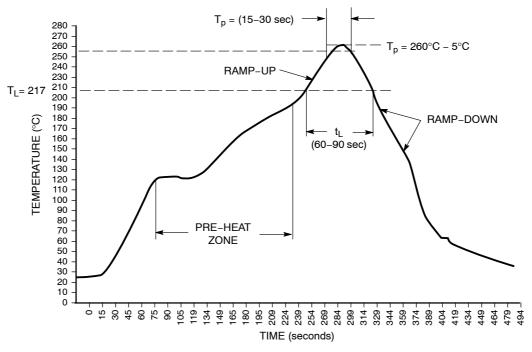
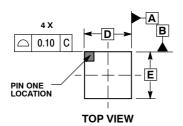
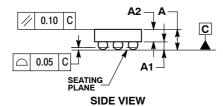


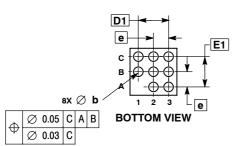
Figure 5. Typical Pb-Free Solder Heating Profile

## PACKAGE DIMENSIONS

8 PIN FLIP-CHIP FC SUFFIX CASE 499AG-01 ISSUE A







#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS.
  COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.700	
A1	0.210	0.270	
A2	0.380	0.430	
D	1.550 BSC		
Е	1.550 BSC		
b	0.290	0.340	
е	0.500 BSC		
D1	1.000 BSC		
E1	1.000 BSC		

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